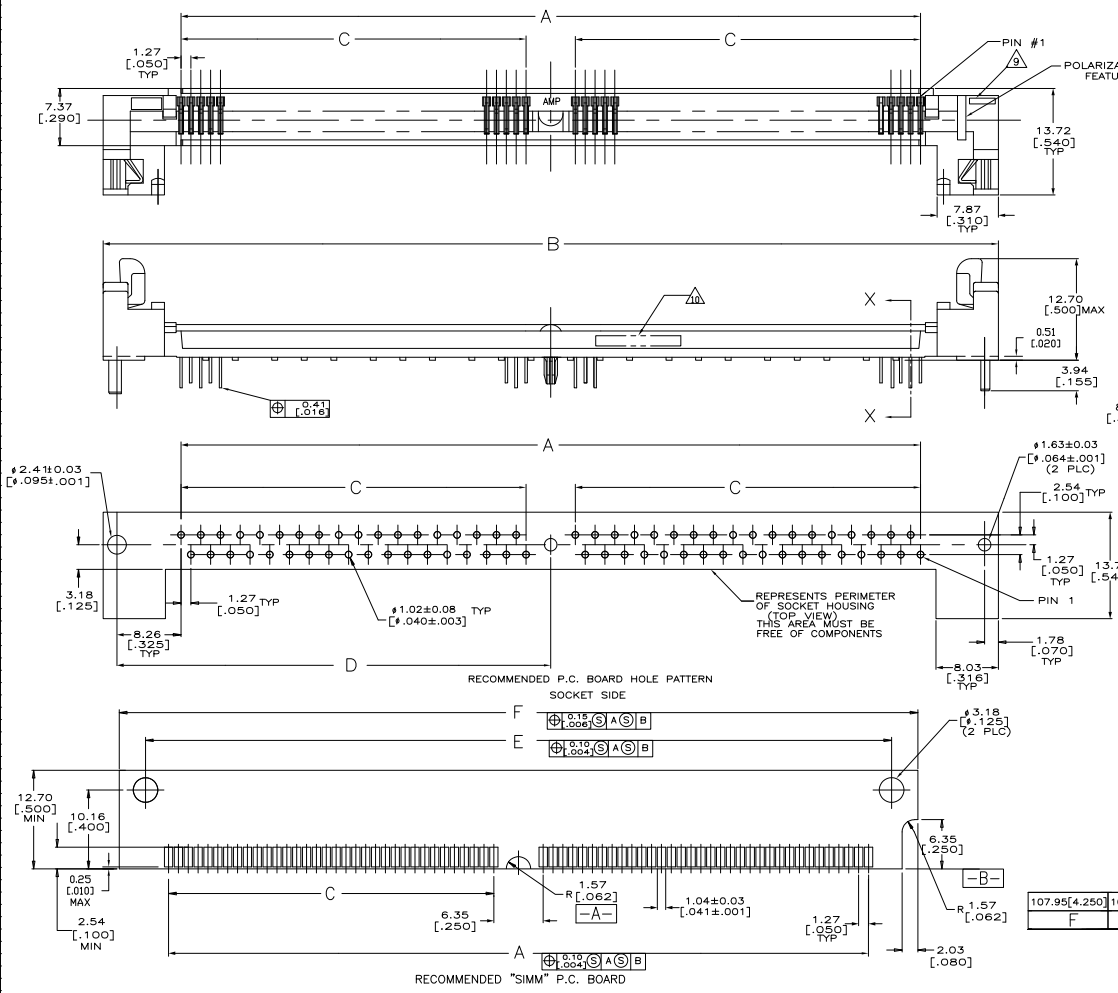
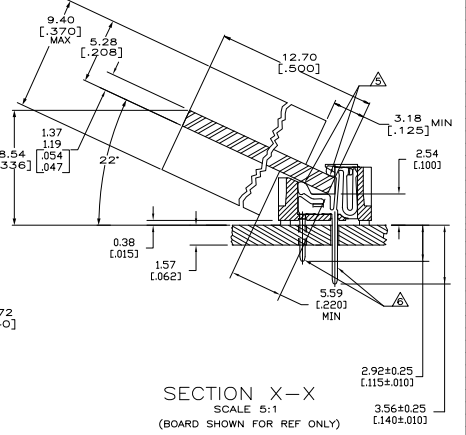


THIS DRAWING IS UNPUBLISHED
 RECEIVED FOR REPRODUCTION
 © 1984 BY THE ELECTRONICS CORPORATION ALL RIGHTS RESERVED

REV	DATE	DESCRIPTION	BY	CHK	APP
GP 00					
V		REVISED PER ECO-06-02941			



- △ HOUSING-MATERIAL : LIQUID-CRYSTAL-POLYMER.
- △ CONTACT-MATERIAL : PHOS. BRONZE.
- △ LATCH-MATERIAL : STAINLESS STEEL.
- △ CONTACT-PLATE 0.00127 [.000050] MIN NICKEL ALL OVER.
- △ CONTACT-PLATE 0.00076[.000030] MIN. GOLD AT CONTACT PTS.
- △ CONTACT SOLDERTAILS-PLATE 0.00508[.000200] MIN TIN/LEAD.
- 7. IN ADDITION TO THOSE RECOMMENDED "SIMM" P.C. BOARD DIMENSIONS AND TOLERANCES SHOWN, ALL JEDEC SPECIFICATIONS APPLY AS SHOWN ON MO-116, ISSUE A.
- 8. RECOMMENDED MATING S.I.M.M. TAB METALLURGY: BASE METAL-COPPER, PLATING TO BE 0.00076[.000030] MIN GOLD OVER 0.00127[.000050] MIN NICKEL.
- △ 'S' IDENTIFIER LOCATED APPROXIMATELY AS SHOWN.
- △ DATE CODE INFORMATION (YEAR WEEK), LOCATED APPROXIMATELY AS SHOWN ON OPPOSITE SIDE ONLY.



107.95[4.250]	101.19[3.984]	55.88[2.200]	44.45[1.750]	115.32[4.540]	95.25[3.750]	72	822137-3
F	E	D	C	B	A	NO. OF PINS	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT		BY	DATE	REVISED	NO. OF PAGES
DRAWN BY		BY	DATE	REVISED	NO. OF PAGES
CHECKED BY		BY	DATE	REVISED	NO. OF PAGES
APPROVED BY		BY	DATE	REVISED	NO. OF PAGES
CUSTOMER DRAWING		DATE	SCALE	SHEET	TOTAL